ABSTRACT OF THE DISCLOSURE

A circular audio amplifier positions the weighty components of its power supply at the bottom, and the audio amplifier portions at the top. Modular finned heat sinks about the audio amplifier portions are resiliently mounted to reduce the transmission of vibration therefrom into the audio amplifier portions. Each module of the heat sink includes copper wires spanning its vertical dimension to short out induced current from top to bottom of the relatively poor electrical conduction of the aluminum of which the heat sinks are made. The audio amplifier portions, except for the final amplifiers, are mounted on independently resiliently mounted parallel substrates. The low-signal substrates are mounted the furthest away from the power supply. All cable entries and exits include grooves surrounding them to suppress the entry of electrical interference. Wires between the power supply and the audio amplifier pass through ferrite beads to filter out high-frequency electrical signals.